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(54) Title: APPARATUS FOR PROCESSING WAFER-SHAPED ARTICLES

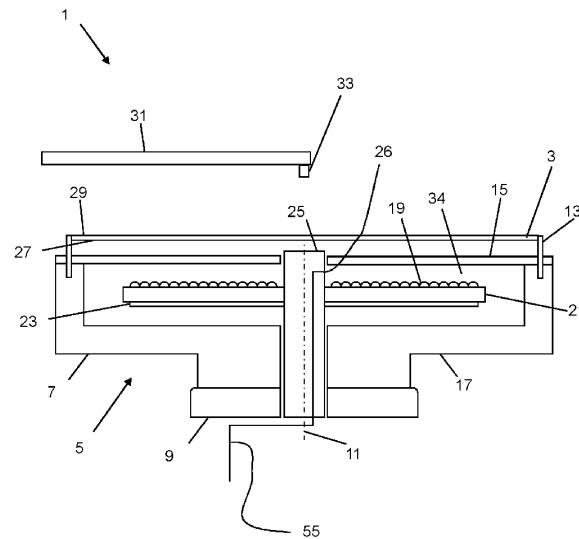


Fig. 1

(57) Abstract: Apparatus for processing wafer-shaped articles, the apparatus comprising: a support configured to support a wafer-shaped article; a heating assembly comprising an array of light-emitting heating elements configured to heat a wafer-shaped article supported by the support; and a gas supply mechanism configured to supply to the array of light-emitting heating elements: a first gas having an oxygen content of less than 1% by volume; and a second gas having an oxygen content that is at least 2% by volume higher than the first gas.

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